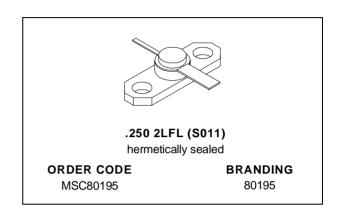
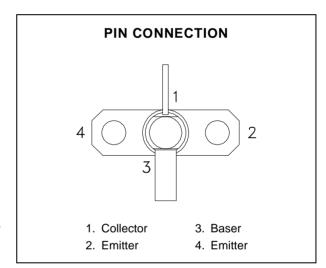


MSC80195

RF & MICROWAVE TRANSISTORS GENERAL PURPOSE LINEAR APPLICATIONS

- EMITTER BALLASTED
- CLASS A LINEAR OPERATION
- COMMON EMITTER
- VSWR CAPABILITY 20:1 @ RATED CONDITIONS
- ft 3.2 GHz TYPICAL
- NOISE FIGURE 12.0 dB @ 2 GHz
- Pout = 28 dBm MIN. @ 2.0 GHz





DESCRIPTION

The MSC80195 is a hermetically sealed NPN power transistor featuring a unique matrix structure. This device is specifically designed for Class A linear applications to provide high gain and high output power at the 1.0 dB compression point.

ABSOLUTE MAXIMUM RATINGS (T_{case} = 25°C)

			T	
Symbol	Parameter	Value	Unit	
P _{DISS}	Power Dissipation (see Safe Area)	_	W	
Ic	Device Bias Current	300	mA	
V _{CE}	Collector-Emitter Bias Voltage*	20	V	
TJ	Junction Temperature	200	°C	
T _{STG}	Storage Temperature	- 65 to +200	°C	

THERMAL DATA

IN H(I-C) JUHCHOH-CASE THEITHAI INESISTANCE JJ JJ C/W	R _{TH(i-c)}	Junction-Case Thermal Resistance*	35	°C/W
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^{*}Applies only to rated RF amplifier operation

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ELECTRICAL SPECIFICATIONS (T_{case} = 25°C)

STATIC

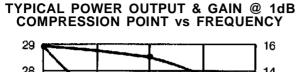
Councile al	Test Conditions	Value			11		
Symbol		Min.	Тур.	Max.	Unit		
ВУсво	$I_C = 1mA$	$I_E = 0mA$		50	_		V
BV _{EBO}	I _E = 1mA	I _C = 0mA		3.5	_	_	V
BVceo	IC = 5mA	$I_B = 0mA$		20	_	_	V
ICEO	V _{CE} = 18V			_	_	0.5	mA
hFE	V _{CE} = 5V	I _C = 100mA		15	_	120	_

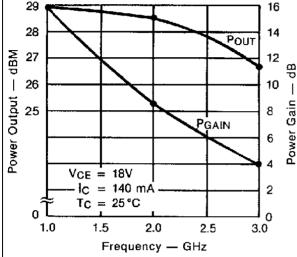
DYNAMIC

Symbol	Took Conditions			Value		Unit	
Symbol	Test Conditions			Min.	Тур.	Max.	Unit
G _P *	f = 2.0 GHz	$P_{OUT} = 28 \text{ dBm}$		_	_	1	dB
ΔG_P^*	f = 2.0 GHz	P _{OUT} = 28 dBm	$\Delta P_{OUT} = 10 \text{ dB}$	7.5	8.5	_	dB
СОВ	f = 1 MHz	V _{CB} = 28 V		_	_	3.0	pF

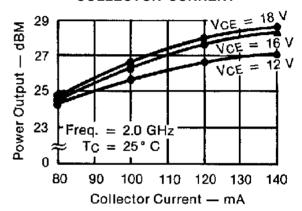
* Note: $V_{CE} = 18 \text{ V}$ $I_{C} = 140 \text{mA}$

TYPICAL PERFORMANCE

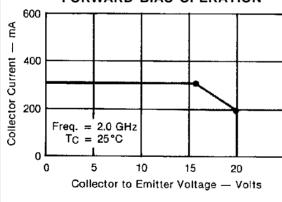




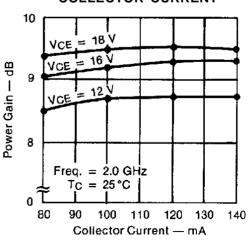




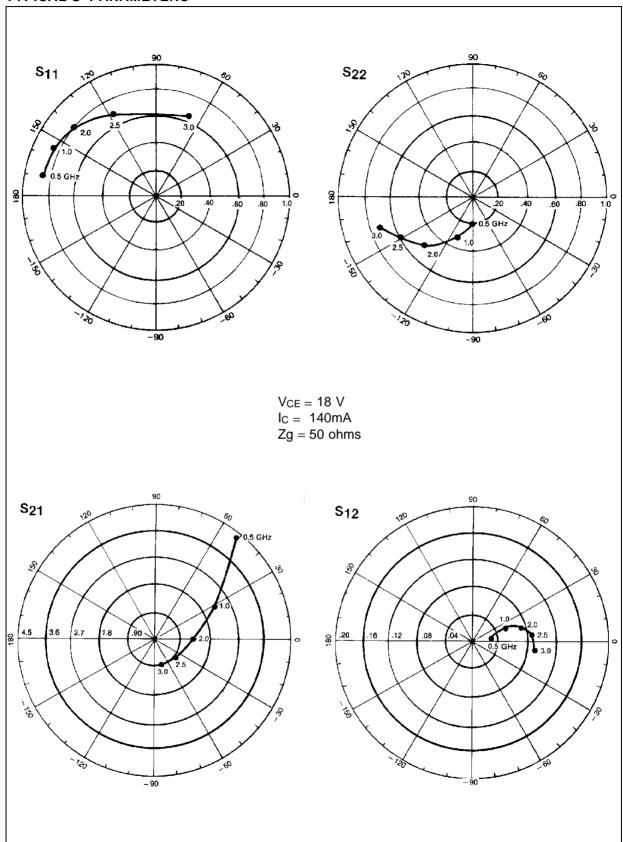
MAXIMUM OPERATING AREA FOR FORWARD BIAS OPERATION



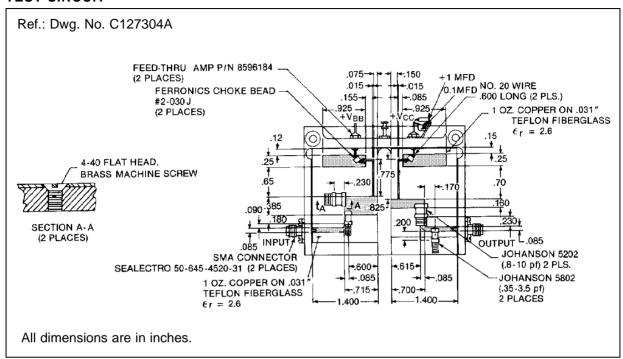
TYPICAL LINEAR GAIN vs COLLECTOR CURRENT



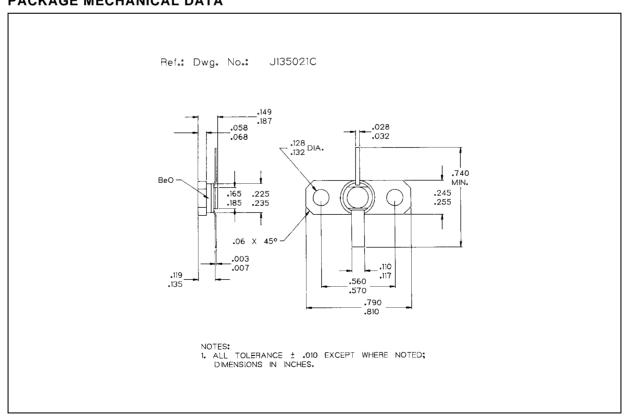
TYPICAL S-PARAMETERS



TEST CIRCUIT



PACKAGE MECHANICAL DATA



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